

# MGF0906B

## L, S BAND POWER GaAs FET

### DESCRIPTION

The MGF0906B, GaAs FET with an N-channel schottky gate, is designed for use in UHF band amplifiers.

### FEATURES

- Class A operation
- High output power  
 $P_{1dB} = 37\text{dBm}$  (TYP) @2.3GHz
- High power gain  
 $G_{LP} = 11\text{dB}$  (TYP) @2.3GHz
- High power added efficiency  
 $\eta_{add} = 40\%$  (TYP) @2.3GHz,  $P_{1dB}$
- Hermetically sealed metal-ceramic package with ceramic lid

### APPLICATION

UHF band power amplifiers

### QUALITY GRADE

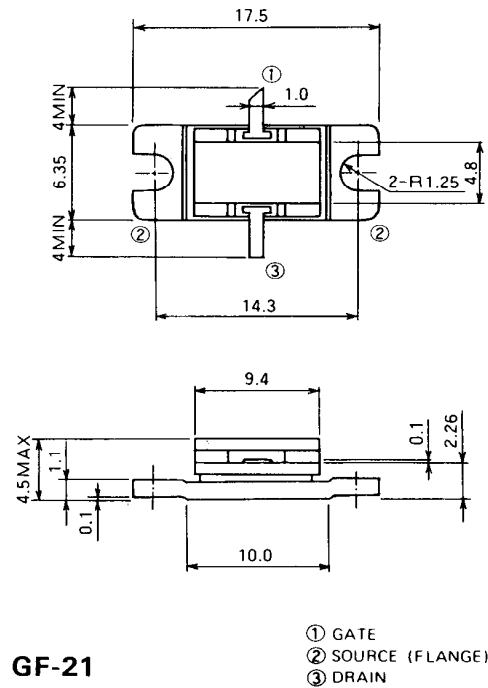
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### RECOMMENDED BIAS CONDITIONS

- $V_{DS} = 10\text{V}$
- $I_D = 1.2\text{A}$
- $R_g = 100\ \Omega$
- Refer to Bias Procedure

### OUTLINE DRAWING

Unit: millimeters



### ABSOLUTE MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

Symbol	Parameter	Ratings	Unit
$V_{GDO}$	Gate to drain voltage	- 15	V
$V_{GSO}$	Gate to source voltage	- 15	V
$I_D$	Drain current	3	A
$I_{GR}$	Reverse gate current	- 10	mA
$I_{GF}$	Forward gate current	+ 21	mA
$P_T$	Total power dissipation *1	23	W
$T_{ch}$	Channel temperature	175	$^\circ\text{C}$
$T_{stg}$	Storage temperature	- 65 ~ + 175	$^\circ\text{C}$

\*1:  $T_c = 25^\circ\text{C}$

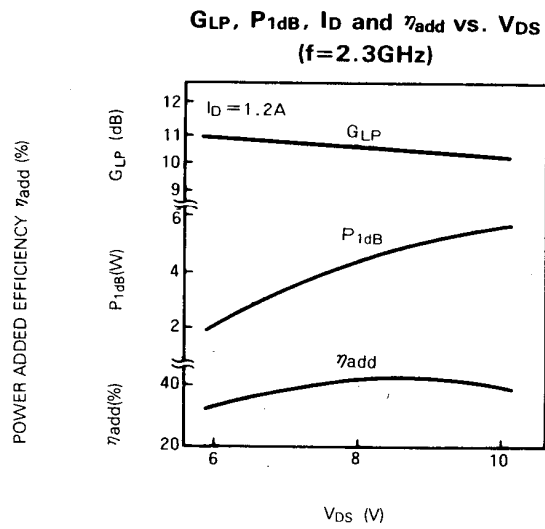
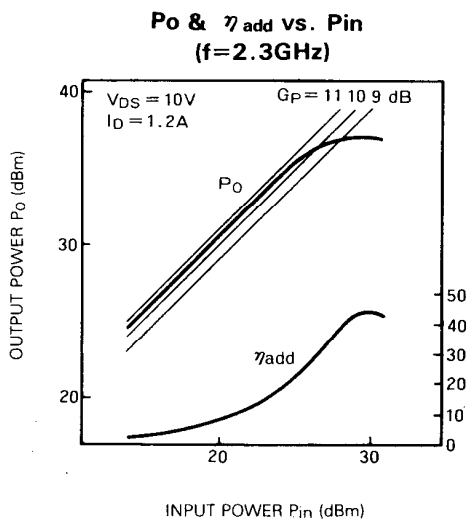
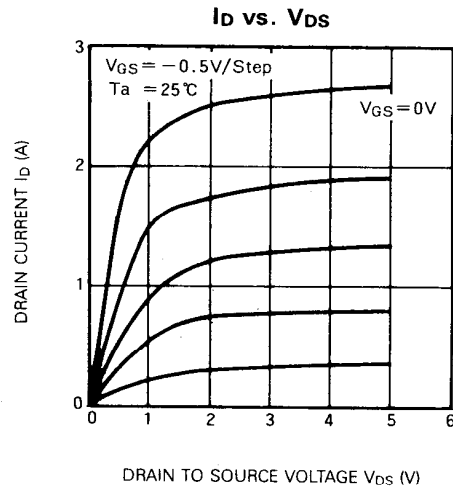
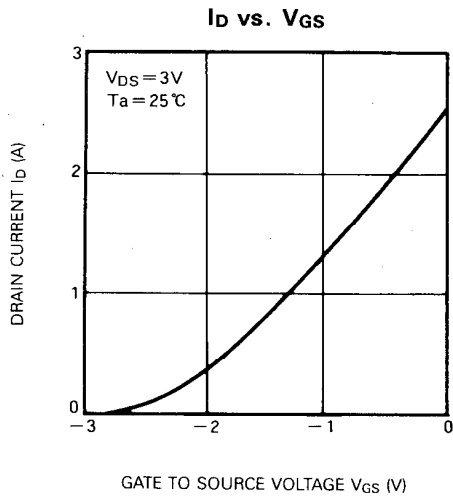
### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$I_{DSS}$	Saturated drain current	$V_{DS} = 3\text{V}, V_{GS} = 0\text{V}$	—	2.0	3.0	A
$g_m$	Transconductance	$V_{DS} = 3\text{V}, I_D = 1.1\text{A}$	—	1.0	—	S
$V_{GS(off)}$	Gate to source cut-off voltage	$V_{DS} = 3\text{V}, I_D = 10\text{mA}$	- 1	- 2.5	- 4	V
$P_{1dB}$	Output power at 1dB gain compression	$V_{DS} = 10\text{V}, I_D = 1.2\text{A}, f = 2.3\text{GHz}$	35.5	37	—	dBm
$G_{LP}$	Linear power gain		10	11	—	dB
$I_D$	Drain current		—	1.1	1.5	A
$\eta_{add}$	Power added efficiency at $P_{1dB}$		—	40	—	%
$R_{th(ch-c)}$	Thermal resistance *1		$\Delta V_f$ method	—	—	6.5

\*1: Channel to case

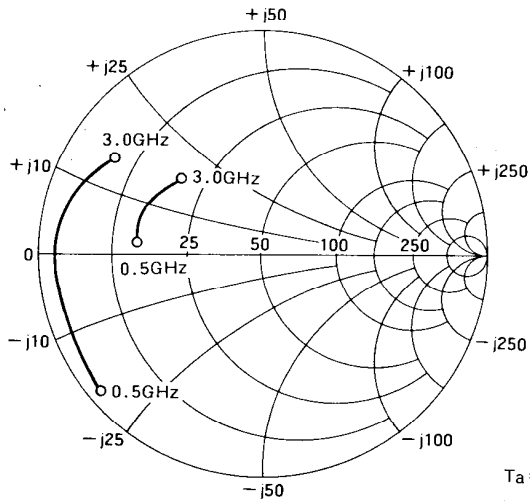
**L, S BAND POWER GaAs FET**

**TYPICAL CHARACTERISTICS**

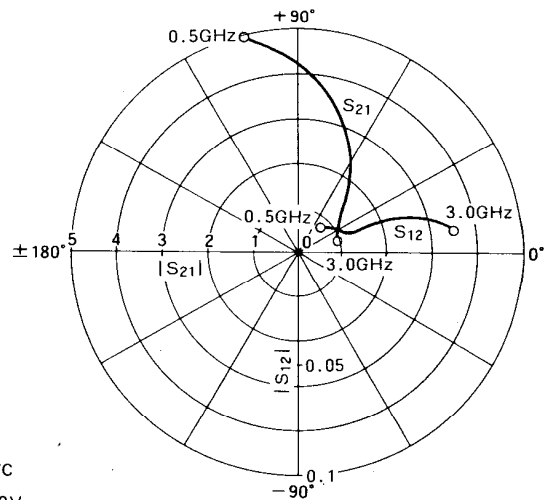


**L, S BAND POWER GaAs FET**

**S<sub>11</sub>, S<sub>22</sub> vs. f**



**S<sub>21</sub>, S<sub>12</sub> vs. f**



T<sub>a</sub> = 25°C  
V<sub>DS</sub> = 10V  
I<sub>D</sub> = 1.2A

**S PARAMETERS** (T<sub>a</sub> = 25°C, V<sub>DS</sub> = 10V, I<sub>D</sub> = 1.2A)

f (GHz)	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>		K	MSG/MAG (dB)
	Magn.	Ang. (deg.)	Magn.	Ang. (deg.)	Magn.	Ang. (deg.)	Magn.	Ang. (deg.)		
0.5	0.922	-139.9	4.997	104.1	0.016	51.5	0.673	174.9	0.869	25.0
0.6	0.913	-146.2	4.570	97.5	0.019	44.9	0.674	172.5	0.837	23.8
0.7	0.906	-151.8	4.176	91.5	0.022	39.3	0.676	170.4	0.807	22.8
0.8	0.900	-156.8	3.815	85.9	0.023	34.6	0.677	168.6	0.826	22.1
0.9	0.896	-161.2	3.484	80.9	0.025	30.7	0.679	167.0	0.819	21.4
1.0	0.894	-165.0	3.182	76.3	0.026	27.7	0.680	165.7	0.834	20.9
1.1	0.892	-168.4	2.909	72.2	0.026	25.2	0.680	164.5	0.883	20.5
1.2	0.891	-171.4	2.662	68.3	0.027	23.4	0.681	163.5	0.906	19.9
1.3	0.891	-174.0	2.440	64.8	0.027	22.1	0.681	162.6	0.959	19.6
1.4	0.891	-176.3	2.242	61.6	0.027	21.3	0.680	161.8	1.024	18.2
1.5	0.892	-178.3	2.067	58.7	0.027	20.9	0.679	161.1	1.086	17.1
1.6	0.892	179.9	1.913	55.9	0.027	20.7	0.678	160.5	1.160	16.1
1.7	0.892	178.2	1.779	53.2	0.028	20.8	0.676	159.8	1.202	15.3
1.8	0.892	176.6	1.664	50.7	0.028	21.0	0.673	159.2	1.285	14.5
1.9	0.891	175.1	1.565	48.2	0.029	21.3	0.670	158.6	1.334	13.9
2.0	0.890	173.6	1.482	45.8	0.030	21.6	0.666	157.9	1.384	13.2
2.1	0.887	172.0	1.414	43.4	0.031	21.9	0.661	157.1	1.455	12.6
2.2	0.883	170.2	1.359	40.8	0.033	21.9	0.655	156.3	1.487	12.0
2.3	0.877	168.3	1.315	38.2	0.035	21.8	0.649	155.3	1.538	11.4
2.4	0.870	166.2	1.282	35.4	0.038	21.3	0.642	154.1	1.553	10.9
2.5	0.861	163.8	1.258	32.5	0.042	20.5	0.633	152.8	1.554	10.4
2.6	0.850	161.1	1.241	29.3	0.046	19.2	0.624	151.3	1.569	9.9
2.7	0.837	157.9	1.231	25.8	0.051	17.4	0.614	149.5	1.569	9.4
2.8	0.821	154.4	1.226	22.0	0.057	15.0	0.602	147.5	1.566	8.9
2.9	0.803	150.3	1.224	17.9	0.064	11.9	0.589	145.1	1.566	8.4
3.0	0.781	145.6	1.224	13.4	0.072	8.0	0.576	142.5	1.549	7.9

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